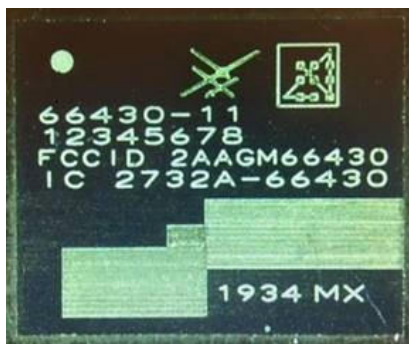


Package Dimensions

The typical part marking for the SKY66430-11 is shown in Figure 6. The PCB layout footprint for the SKY66430-11 is shown in Figure 7. Package dimensions are shown in Figure 8, and tape and reel dimensions are provided in Figure 9.



Package and Handling Information

Since the device package is sensitive to moisture absorption, it is baked and vacuum packed before shipping. Instructions on the shipping container label regarding exposure to moisture after the container seal is broken must be followed. Otherwise, problems related to moisture absorption may occur when the part is subjected to high temperature during solder assembly.

The SKY66430-11 is rated to Moisture Sensitivity Level 3 (MSL3) at 260 °C. It can be used for lead or lead-free soldering. For additional information, refer to the Skyworks Application Note, *Solder Reflow Information*, document number 200164.

Care must be taken when attaching this product, whether it is done manually or in a production solder reflow environment. Production quantities of this product are shipped in a standard tape and reel format.

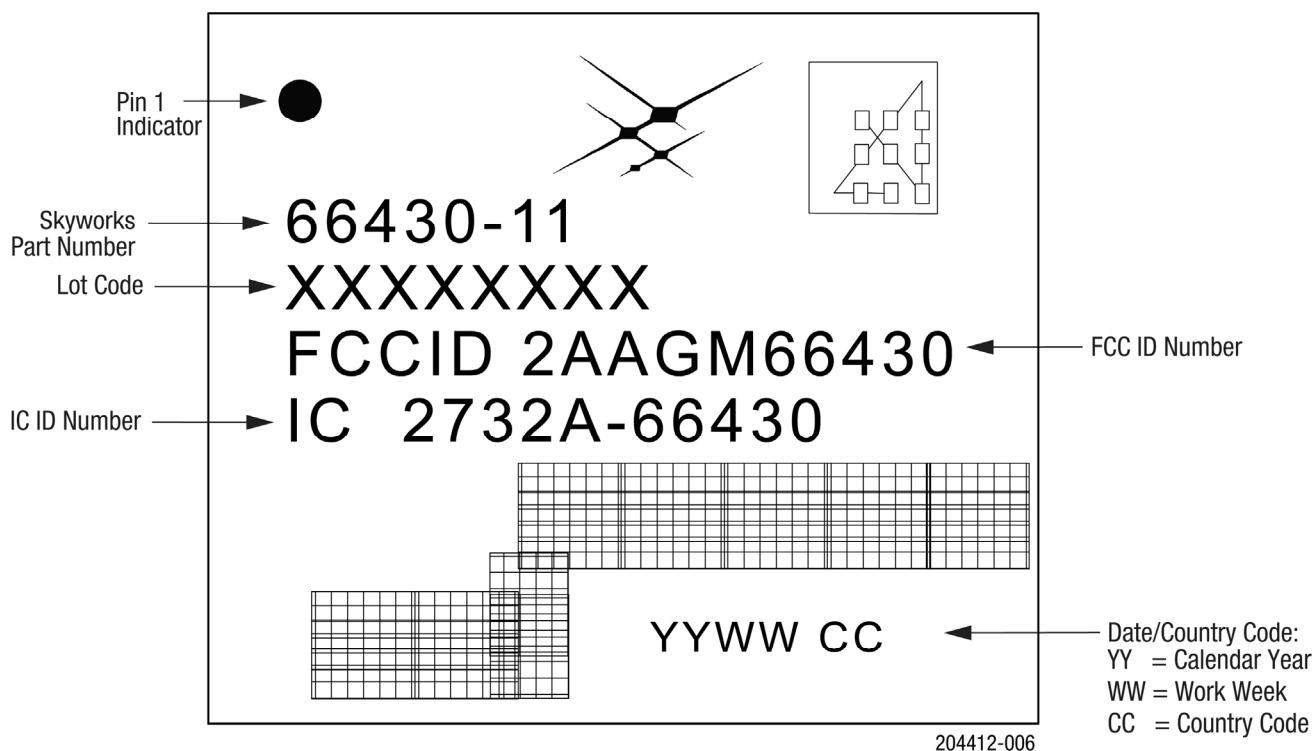


Figure 6. SKY66430-11 Typical Part Marking